

Features & Application

- Higher inductance values than other 0603 inductors
- Ferrite construction for high current handling
- Inductance values: 47 nH – 22 μH; 5% ,10%and 20% toler

Core material Ferrite

Environmental RoHS compliant, halogen free

Terminations Silver-palladium-platinum-glass frit. Other term available at additional cost.

Ambient temperature -40°C to +125°C with Irms current

Maximum part temperature +140°C (ambient + temp rise).

Storage temperature Component: -40°C to +140°C.

Tape and reel packaging: -40°C

Resistance to soldering heat Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles

Temperature Coefficient of Inductance (TCL) +25 to +125 ppm/°C

Moisture Sensitivity Level (MSL) 1 (unlimited floor life at <30°C /

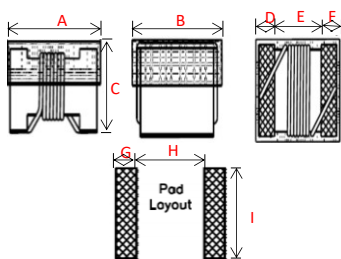
85% relative humidity)



★ When ordering, please check part number

Part number	Inductance 7.96MHz (uH)	Inductance Tolerance	Q (min) 7.96MHz	RDC (Ω) Max	IRMS (mA)	SRF (GHz) Min.
SF11608P-47N□T	0.047	K,M	10	0.075	1500	1.700
SF11608P-72N□T	0.072	K,M	10	0.12	1500	1.700
SF11608P-R10□T	0.10	K,M	10	0.13	1400	1.150
SF11608P-R12□T	0.12	K,M	10	0.15	1400	1.100
SF11608P-R15□T	0.15	K,M	10	0.15	1300	1.050
SF11608P-R18□T	0.18	K,M	10	0.15	950	0.950
SF11608P-R22□T	0.22	K,M	10	0.15	710	0.800
SF11608P-R27□T	0.27	K,M	10	0.20	620	0.775
SF11608P-R33□T	0.33	K,M	10	0.35	600	0.725
SF11608P-R39□T	0.39	K,M	10	0.39	570	0.620
SF11608P-R47□T	0.47	K,M	10	0.43	550	0.540
SF11608P-R56□T	0.56	K,M	10	0.47	470	0.525
SF11608P-R68□T	0.68	K,M	10	0.68	400	0.460
SF11608P-R82□T	0.82	K,M	10	0.80	400	0.410
SF11608P-1R0□T	1.00	J,K	10	0.81	370	0.190
SF11608P-1R2□T	1.20	J,K	10	0.87	350	0.160
SF11608P-1R5□T	1.50	J,K	10	0.96	350	0.100
SF11608P-1R8□T	1.80	J,K	10	1.1	320	0.080
SF11608P-2R2□T	2.20	J,K	10	1.2	290	0.068
SF11608P-2R7□T	2.70	J,K	10	1.3	280	0.050
SF11608P-3R3□T	3.30	J,K	10	1.5	280	0.042
SF11608P-3R9□T	3.90	J,K	10	1.6	270	0.040
SF11608P-4R2□T	4.20	J,K	10	2.0	260	0.036
SF11608P-4R7□T	4.70	J,K	10	2.1	240	0.034
SF11608P-5R6□T	5.60	J,K	10	2.6	200	0.032
SF11608P-6R8□T	6.80	J,K	10	3.1	190	0.031
SF11608P-8R2□T	8.20	J,K	10	4.4	400	0.026
Part number	Inductance 2.52MHz (uH)	Inductance Tolerance	Q min MHz	RDC (Ω) Max	IRMS (mA)	SRF (GHz) Min.
SF11608P-100□T	10	J,K	10	4.8	180	0.025
SF11608P-150□T	15	J,K	10	6.8	130	0.020
SF11608P-180□T	18	J,K	10	6.8	100	0.016
SF11608P-220□T	22	J,K	10	8.0	80	0.013

Isolation (Vrms) : 250V. Winding to winding isolation (hipot) tested for one minute.



Dimensions	
A	1.80 MAX
B	1.20 MAX
C	1.20 MAX
D	0.45 TYP
E	0.90 TYP
F	0.45 TYP
G	0.64 TYP
H	0.64 TYP
I	1.02 TYP
unit : mm	

Impedance/Inductance/Q/ LCR Angilent E4991A

Resistance DC Chroma 16502

Current per winding that causes a 20°C rise from 25°C ambie

Electrical specifications at 25°C

Weight 4.2 – 7.3 mg.

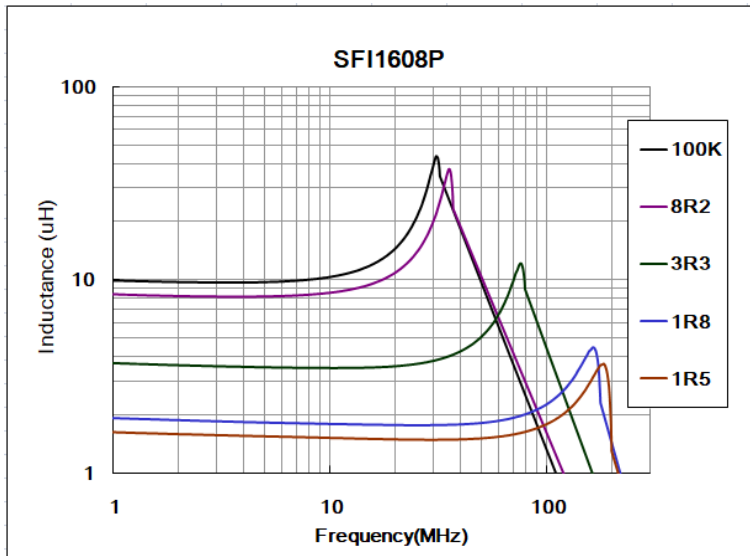
Packaging 2000/7 # reel; Plastic tape: 8 mm wide.

Packaging will different,accroding the various chip size.

Contact Us	
US	sales-us@bing-ri.com.tw
Taiwan	sales-tw@bing-ri.com.tw
China	sales-cn@bing-ri.com.tw
Japan	sales-jp@bing-ri.com.tw

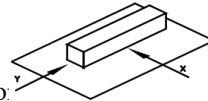
Official Website :	
<a href="https://www.bing-ri.com.tw/">https://www.bing-ri.com.tw/</a>	

Typical Inductance vs Frequency



GENERAL CHARACTERISTICS

1. Operating temperature range:  $-40$  TO  $+125^{\circ}\text{C}$  (Includes temperature when the coil is heated)
2. External appearance: On visual inspection, the coil has no external defects.
3. Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Y withstanding at below conditions.  
Terminal should not peel off. (refer to figure at right) 0.5kg Min -1608
4. Insulating resistance: Over  $100\text{M}\Omega$  at  $100\text{V D.C.}$  between coil and core.
5. Dielectric strength: No dielectric breakdown at  $100\text{V D.C.}$  for 1 minute between coil and core
6. Temperature characteristics: Inductance coefficient  $(0\sim 2,000)\times 10^{-6}/(^{\circ}\text{C } -25\sim +80)$ .  $^{\circ}\text{C}$ , inductance deviation within  $\pm 5.0\%$ , after 96 hours.
7. Humidity characteristics (Moisture Resistance): Inductance deviation within  $\pm 5\%$ , after 96 hours in  $90\sim 95\%$  relative humidity at  $40 \pm 2$  and 1 hour drying under normal condition.
8. Vibration resistance: Inductance deviation within  $\pm 5\%$ , after vibration for 1 hour. In each of three orientations at sweep vibration ( $10\sim 55\sim 10$  Hz) with  $1.5\text{mm P-P}$  amplitudes.
9. Shock resistance: Inductance deviation within  $\pm 5\%$ , after being dropped once with  $981\text{m/s}^2$  ( $100\text{G}$ ) shock attitude upon a rubber block method shock testing machine, in three different
10. Resistance to Soldering Heat: 260, 10 seconds (See attached recommend reflow)
11. Storage environment: Storage condition: Temperature Range:  $10 \sim 35$  (Generally:  $21 \sim 31$ ), Humidity Range:  $50\% \sim 80\%$  RH (Generally:  $65\% \sim 75\%$ ); Transportation condition: Temperature Range:  $-35 \sim 85$ , Humidity Range:  $50\% \sim 95\%$  RH
12. Use components within 12 months. If 12 months or more have elapsed, check solderability before use.
13. Reflow profile recommend:



Lead-free heat en duran ce test

Lead-free the recommended reflow condition

